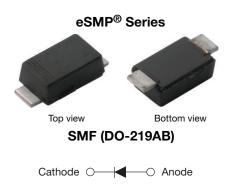


Ultrafast Rectifier, 2 A FRED Pt®



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS				
I _{F(AV)}	2 A			
V _R	600 V			
V _F at I _F	0.95 V			
t _{rr}	55 ns			
T _J max.	175 °C			
Package	SMF (DO-219AB)			
Circuit configuration	Single			

FEATURES

• Ultrafast recovery time, reduced Q_{rr}, and soft recovery



COMPLIANT

• 175 °C maximum operating junction temperature

• For PFC CRM, snubber operation

HALOGEN FREE

· Low forward voltage drop

Low leakage current

• Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Meets JESD 201 class 2 whisker test

• Wave and reflow solderable

Compatible to SOD-123W package case outline

• Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art ultrafast recovery rectifiers designed with optimized performance of forward voltage drop, ultrafast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in PFC, boost, lighting, in the AC/DC section of SMPS, freewheeling and clamp diodes

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per

J-STD-002

Polarity: color band denotes cathode end

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	I _{F(AV)}	T _C = 135 °C ⁽¹⁾	2	۸
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C, 6 ms square pulse	30	А
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +175	°C

Note

(1) Device on PCB with 8 mm x 16 mm soldering lands



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	600	-	-	
Forward voltage	V	I _F = 2 A	-	1.10	1.35	V
Forward voitage	V _F	I _F = 2 A, T _J = 150 °C	-	0.95	1.15	
Reverse leakage current I _R	V _R = V _R rated	-	-	3		
	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	20	100	μA	
Junction capacitance	C _T	$V_{R} = 600 \text{ V}$	-	5	-	pF

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		1	42	-	
Reverse recovery time	+	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr}$	= 1 A, I _{rr} = 0.25 A		-	55]
neverse recovery time	t _{rr}	T _J = 25 °C	I _F = 2 A	-	40	-	ns ns
		T _J = 125 °C		-	63	-	
Dools recovery as week		T _J = 25 °C		-	7.0	-	^
Peak recovery current I _{RRM}	T _J = 125 °C	dl _F /dt = 500 A/µs V _R = 400 V	-	8.1	-	Α	
Daylorea recovery charge)	T _J = 25 °C		-	140	-	nC
Reverse recovery charge	Q _{rr}	T _J = 125 °C		ı	255	-	TIC

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	+175	°C
Thermal resistance, junction to mount	R _{thJM}	Device mounted on PCB with 8 mm x 16 mm soldering lands	-	-	15	°C/W
Thermal resistance, junction to ambient	R _{thJA}	Device mounted on PCB with 2 mm x 3.5 mm soldering lands	-	-	130	°C/W
Approximate weight				0.015	-	g
Approximate weight				0.0005		OZ.
Marking device		Case style SMF (DO-219AB)		M	PU	

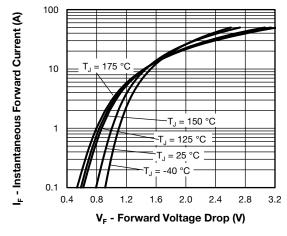


Fig. 1 - Typical Forward Voltage Drop Characteristics

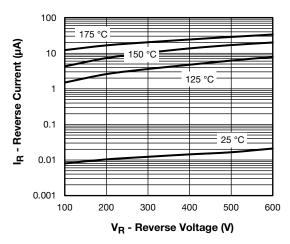


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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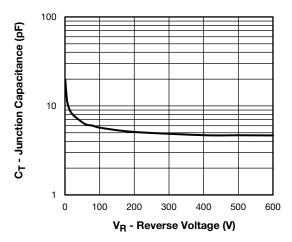


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

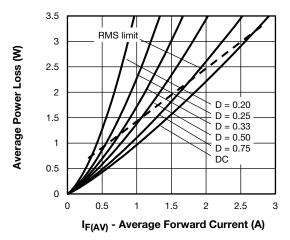


Fig. 5 - Forward Power Loss Characteristics

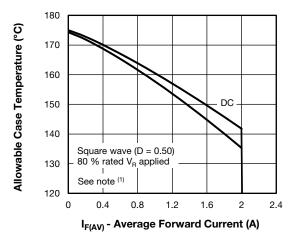


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

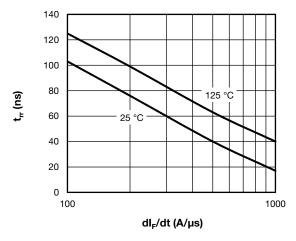


Fig. 6 - Typical Reverse Recovery Time vs. dl_F/dt

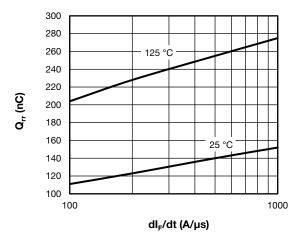
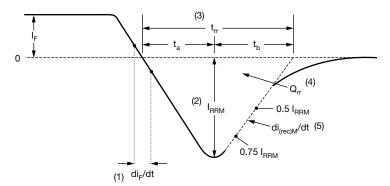


Fig. 7 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 5)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

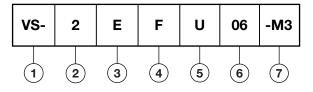
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 8 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- Vishay Semiconductors product
- Current rating (2 = 2 A)
- 3 Circuit configuration:

E = single diode

- 4 F = SMF package
- 5 Process type,

U = ultrafast recovery

- 6 Voltage code (06 = 600 V)
- 7 -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

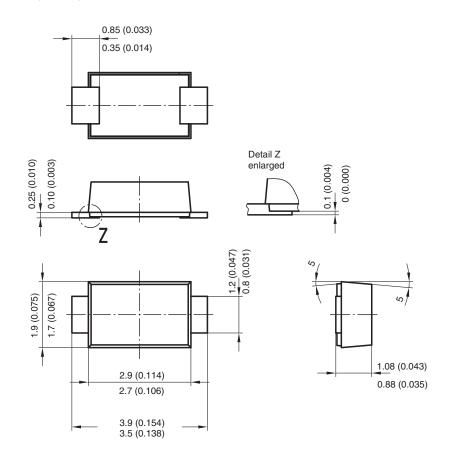
ORDERING INFORMATION (Example)						
PREFERRED P/N	PREFERRED P/N QUANTITY PER REEL MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION					
VS-2EFU06-M3/I	10 000	10 000	13"diameter plastic tape and reel			

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95572</u>				
Part marking information	www.vishay.com/doc?95618			
Packaging information	www.vishay.com/doc?95577			
SPICE model	www.vishay.com/doc?96867			

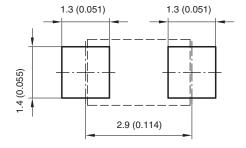


SMF (DO-219AB)

DIMENSIONS in millimeters (inches)



Foot print recommendation:



Created - Date: 15. February 2005 Rev. 3 - Date: 13. March 2007 Document no.:S8-V-3915.01-001 (4) 17247



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